

**SEMI-AUTOMATIC TAB BONDING MACHINE
BONDING OF TAB TO TFT & PCB (PWB)
TM-118P-TFT**



OVERVIEW

High performance Semi-Automatic TAB Bonding Machine TM-118P-TFT is specifically designed for bonding of TAB to LCD and PCB of TFT panels up to 10-23 inches. TM-118P-TFT is also well suited for TAB rework applications. This system is able to perform soldering of TAB substrates to PCB. By changing the polyamide tape with a silicone rubber, the machine can be used to perform ACF bonding of TAB to TFT panels.

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FEATURES & BENEFITS

- Microprocessor based pulse heat controller
- 4 stage ramp temperature
- Multiple indexing of up to 15 positions
- **Intelli-Pulse** system offers fast and accurate temperature control as system parameters are automatically adjusted
- Real time temperature profile display on LCD touch panel
- Colour CCD camera for fine pitch alignment
- Light source for CCD camera
- Silicone rubber or polyamide tape indexing spool
- Leveling mechanism for co-planarity adjustment
- 40 programmable profiles
- User pre-set password

APPLICATIONS

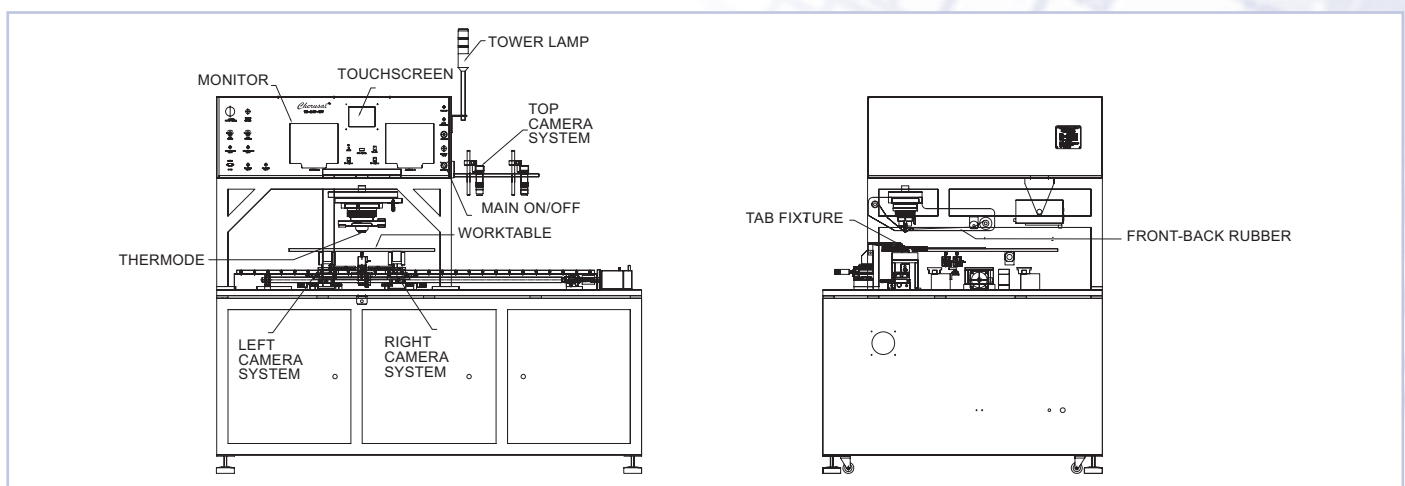
- Ability to perform TAB Bonding and Hot Bar Soldering of TAB to TFT and PCB (PWB)
- Suitable for large TFT panels measuring at 10-23 inches

SPECIFICATIONS

Heating Method	Pulse Heat
Power Requirement	230VAC ±10% 50/60 Hz, 3.5kVA
Operating Ambient	10-40°C, 40 to 100°C humidity with no significant dust
Supply Pressure	Filtered clean air, 5-7 kgf / cm ²
Visual Aids	2 units of colour CCD (at bottom) 2 units of colour CCD (at top)
Magnification	150X (Top vision system) 260X (Bottom vision system)
Work Table Size	650mm x 650mm
Monitors	10.4" TFT monitors
LCD Size	10" to 23"
PCB Size	X: 90mm x Y: 10mm ~ X: 530mm x Y: 100mm
Indexing	Selectable 15 position for bonding

User Interface	LCD Touch Panel
Programmable Profiles	40
Dimensions	1900mm (L)x 1250mm (W)x 1683mm (H)
Weight	Approx. 900kg
Pulse Heating Specifications	
Bonding Force	4kgf - 72kgf
Temperature Ramp Profile	4 stages
Start Temp.	30°C to 300°C
Ramp Temp.	30°C to 400°C
Ramp Period	1 to 25 seconds
Hold Period	1 to 100 seconds
Release Temp	30°C to 400°C
Thermode Specifications	
Max. Thermode Size	65mm x 2mm
Thermocouple Type	K Type

Specifications are subjected to change without prior notice



HEADQUARTER (SINGAPORE)



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